



Material Content Data Sheet



Sales Product Name		ICB1FL02G		Issued		19. July 2018			
MA#		MA000886202							
Package		PG-DSO-18-2		Weight*		591.45 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.328	0.90	0.90	9009	9009	
leadframe	inorganic material	phosphorus	7723-14-0	0.042	0.01		71		
		non noble metal	zinc	7440-66-6	0.169	0.03		285	
		non noble metal	iron	7439-89-6	3.377	0.57		5709	
encapsulation	organic material	non noble metal	copper	7440-50-8	137.116	23.18	23.79	231829	237894
		carbon black	1333-86-4	0.876	0.15		1481		
		plastics	epoxy resin	-	40.301	6.81		68140	
leadfinish	inorganic material	silicondioxide	60676-86-0	396.881	67.10	74.06	671026	740647	
		non noble metal	tin	7440-31-5	2.998	0.51	0.51	5068	5068
plating	noble metal	silver	7440-22-4	1.382	0.23	0.23	2337	2337	
glue	plastics	epoxy resin	-	0.746	0.13		1261		
		noble metal	silver	7440-22-4	2.238	0.38	0.51	3784	5045
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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